



# PRODUCT/PROCESS CHANGE NOTIFICATION

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PCN CPG-CSD/07/2510  
Notification Date 05/10/2007

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**PDIP PACKAGE CONVERSION FROM DIPPING TO PRE-PLATED FRAME**

**CSD - COMPUTER SYSTEM**

**Table 1. Change Identification**

Product Identification (Product Family/Commercial Product)	see attached
Type of change	Package assembly material change
Reason for change	Company Roadmap
Description of the change	see attached
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	see attached
Manufacturing Location(s)	

**Table 2. Change Implementation Schedule**

Forecasted implementation date for change	29-Jun-2007
Forecasted availability date of samples for customer	31-May-2007
Forecasted date for <b>STMicroelectronics</b> change Qualification Plan results availability	03-May-2007
Estimated date of changed product first shipment	09-Aug-2007



## DOCUMENT APPROVAL

Name	Function
Mazzola, Matteo	Division Marketing Manager
Peduto, Vittorio	Division Product Manager
Pennati, Silvia Maria	Division Q.A. Manager

## **PCN: PDIP PACKAGE CONVERSION FROM DIPPING TO PRE-PLATED FRAME**

### **WHAT:**

The purpose of this PCN is to inform our customers as far as the conversion from Dipping to Pre-Plated Frame on PDIP 16 cu.25 packages assembled in STM Shenzhen fab.

The following changes have been implemented:

	<b>DIPPING</b>	<b>PPF</b>
Die Attach	Glue Ablebond 8390	Loctite QMI168
Wire	Gold 1.5 mils	Gold 1.5 mils
Resin	KCC KTMC1000 1030SL	KCC KTMC1000 1030SL
Lead Finish	Pure Sn (e3)	NiPdAu (e4)
Lead Frame	PDIP16 IDF Cu	PDIP 16 PPF
Marking	Jedec e3 (Sn) logo	Jedec e4 (NiPdAu) logo

### **WHY:**

Company Roadmap

### **HOW:**

The qualification of the new assy BOM was achieved by extension: no additional Reliability trials is planned.

The Package Qualification Certificate (QC-82-05 HPC) is available upon request.

### **WHEN:**

We will start from June 2007 onward to migrate into the PDIP16 cu.25 Pre-Plated Frame

### **DEVICES INVOLVED:**

Here below the list of the devices involved in this change:

Line code	Commercial Product codes
3717	E-TEA3717DP
3718	E-TEA3718DP E-TEA3718SDP
3719	E-IL13528
L736	E-L6210

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